HP Elite x2 G4



- 1. Audio-out/Audio-in Combo Jack
- 2. Speakers
- 3. Volume Up/Volume Down
- 4. Nano Security Lock Slot (Lock sold separately)
- 5. Magnetic Pen Attach Area

Left

- 6. Glass Clickpad
- 7. Optional Collaboration Keyboard
- 8. IR Cam LED
- 9. Hybrid Webcam and IR Camera
- 10. Webcam LED



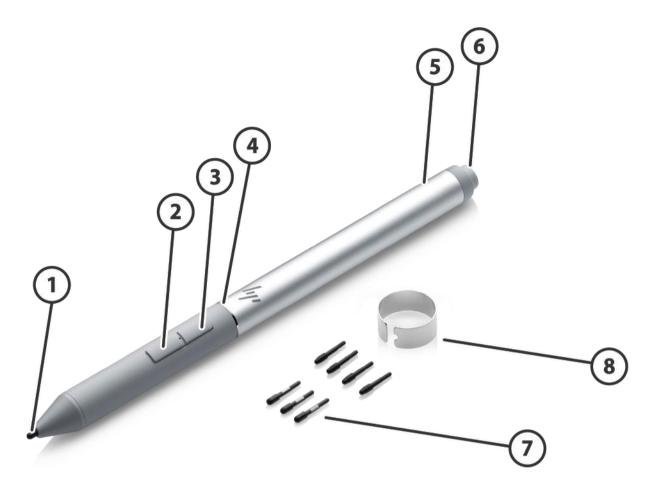


Right

- **Charging LED** 1.
- 2. USB Type-C™ charging port
- 3. USB Type-C™ with Thunderbolt™
- USB Type-C™ with Thunderbolt™ 4.
- Nano SIM Card Slot (Available on configurations with 11. World-Facing Microphone WWAN only)1
- Kickstand

- 7. Optional Fingerprint Sensor (select models)
- 8. Power Button
- 9. Privacy Camera Shutter
- 10. Rear-Facing Webcam

1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug.



HP Rechargeable Active Pen G3

- 1. Tip
- 2. Erase
- 3. Select
- 4. Diamond-Cut Ring
- 1. Sold separately or as an optional accessory

- 5. USB-C Charging Port (System AC adapter may be used to charge the pen)
- 6. Bluetooth Pairing / Application Launch
- 7. Spare Pen Tips (3 elastomer tips, 4 POM tips. POM tips are recommended for use with anti-glare panels)
- 8. Pen Tip Removal Tool



At a Glance

- Designed for full PC performance and pure tablet freedom in an exquisite, fully-optimized detachable design featuring authentic materials and thoughtful finishes
- 8th Generation Intel® Core™ (U-series) processors, some with vPro™ support¹
- Up to 14 hours and 15 minutes of battery life²
- Windows 10 versions or FreeDOS
- Choice of displays:
 - 13" diagonal WUXGA+ 1000 nits Ultraslim bent 72% CG with HP Sure View Gen3 (1920 x 1280)*
 - 13" diagonal 3kx2k 450 nits Ultraslim bent 72% CG (3000 x 2000)
 - 12.3" diagonal WUXGA+ 400 nits Ultraslim 72% CG (1920 x 1280)
 - 13" diagonal WUXGA+ 650 nits Ultraslim 72% CG with HP Sure View Gen2 (1920 x 1280)*
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles³
- Weight starting at 830 g (1.83 lbs) for tablet
- Height starting at 8.8 mm (.35 inches) for tablet
- Supports up to gigabit speed LTE for a range of wireless broadband options for connectivity on the go
- Front and back-facing webcams
- Audio by Bang & Olufsen
- Three microphone array featuring a rear-facing microphone with HP Advanced Noise Reduction to improve inbound ambient noise cancellation
- Enterprise grade security with HP Sure Sense⁶, HP SureStart Gen5, HP Privacy Camera, HP Sure View Gen3⁵, HP Sure Run Gen2, HP Sure Recover Gen2, HP Sure Click, self-encrypting storage drives, a built-in IR camera and an optional Fingerprint Sensor⁷ (select models)
- Passed 19 MIL-STD 810G tests⁴
- Standard commercial 1 year limited warranty with extended service available with optional HP Care Packs
- 1. vPro[™] support not available on all configurations
- 2. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage.
- 3. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 4. MIL-STD-810G testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- 5. HP Sure View Gen3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 6. HP Sure Sense requires Windows 10. See product specifications for availability. On HP Elite x2 G4 units with WWAN shipping to China, HP Sure Sense is only available via Softpaq download.
- 7. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.
- *Touch-enabled display and Sure View privacy panel will lower actual brightness



PRODUCT NAME

HP Elite x2 G4

OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64¹

Windows 10 Pro 64 (National Academic only)2

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)1

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel® Core™ i7-8665U vPro™ with Intel® UHD graphics 620 (1.9 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,7}

Intel® Core™ i7-8565U with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i5-8365U vPro™ with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology. 6 MB L3 cache. 4 cores)^{3,4,5,7}

Intel® Core™ i5-8265U with Intel® UHD Graphics 620 Graphics (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Processor Family

8th Generation Intel® Core™ i7 processor (i7-8665U, i7-8565U models)⁵ 8th Generation Intel® Core™ i5 processor (i5-8365U, i5-8265U models)⁵

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.
- 7. For full Intel® vPro™ functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See http://Intel.com/vpro.



CHIPSET

Integrated with processor

GRAPHICS

Integrated

Intel® UHD graphics 620

Supports

Support HD decode, DX12, HDMI 1.4b8

8. HD content required to view HD images.

DISPLAY

Touch

33.02 cm (13") diagonal 3kx2k IPS BrightView WLED-backlit Ultraslim bent touch screen with Corning® Gorilla® Glass 5 450 nits, 72% NTSC (3000x2000)^{8,9,10}

33.02 (13") diagonal WUXGA+ IPS eDP WLED-backlit ultra slim bent touch screen with Corning® Gorilla® Glass 5 and HP Sure View integrated privacy screen Gen3, 1000 nits, 72% NTSC (1920 x 1280)^{8,9,10,11,*}

33.02 (13") diagonal WUXGA+ IPS eDP WLED-backlit ultra slim touch screen with Corning® Gorilla® Glass 5 and HP Sure View integrated privacy screen Gen2, 650 nits, 72% NTSC (1920 x 1280)^{8,9,10,12,*}

31.24 cm (12.3") diagonal WUXGA+ IPS BrightView WLED-backlit Ultraslim touch screen with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC (1920x1280)^{8,9,10}

- 8. HD content required to view HD images.
- 9. Sold separately or as an optional feature.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. HP Sure View Gen3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 12. HP Sure View Gen2 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- *Touch-enabled display and Sure View privacy panel will lower actual brightness





Docking station model	Total number of supported displays (incl. the notebook) display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock G2	3	Dual 4K @ 60Hz	TXO2B-C att-mode	Dual 4k (4096 x 2160) only with: • 1 DP + TB port or • USB-C alt mode + TB port Dual 4K (3840 x 2160) with any of the DP, TB or USB-C alt mode video ports
HP Elite USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary M.2 Storage

2 TB PCle® Gen3x4 NVMe™ SS TLC¹³

1 TB PCIe® Gen3x4 NVMe™ SS TLC¹³

512 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10^{13,14,15}

512 GB PCIe® Gen3x4 NVMe™ SS TLC Opal 213

512 GB PCIe® Gen3x4 NVMe™ SS TLC¹³

512 GB PCIe® NVMe™ SS Value¹³

256 GB SATA-3 SED TLC Opal 213

256 GB PCIe® Gen3x4 NVMe™ SS TLC13

256 GB PCIe® NVMe™ SS Value¹³

256 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 16 GB Intel® Optane™ memory H10^{13,14,15}

128 GB SATA-3 SS TLC¹³

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

14. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

15. Intel® Optane™ memory H10 only for Intel® PCIe® NVMe™ QLC M.2 SSD.



MEMORY

Maximum Memory

16 GB LPDDR3-2133 SDRAM15

Memory

16 GB LPDDR3-2133 SDRAM (2 X 8 GB)¹⁶ 8 GB LPDDR3-2133 SDRAM (2 x 4 GB)¹⁶

Memory Slots

Memory soldered down Supports Dual Channel Memory

16. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WI AN

Intel® Wi-Fi 6 AX200 + BT5 (802.11ax 2x2, vPro*, supporting gigabit file transfer speeds)^{™17,18} Intel® Wi-Fi 6 AX200 + BT5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds)^{™17,18}

WWAN

Intel® XMM™ 7360 LTE-Advanced Cat 9¹⁹
Intel® XMM™ 7560 LTE-Advanced Pro Cat 16²⁰

Miracast

Native Miracast Support²¹

Standalone GPS

HP Graff GNSS Module²²

HP Connection Optimizer

Support HP Connection Optimizer

- 17. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.
- 18. Dynamic Regulatory Solution will auto-change AC WLAN to about by passive scan when entering Indonesia.
- 19. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 20. Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 21. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 22. Standalone GPS is an optional feature and requires factory configuration. GPS and WWAN are mutually exclusive.
- * For full Intel® vPro™ functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See http://Intel.com/vpro.



AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen
2 Premium stereo speakers (74 dB)

Maximum System Acoustic level: 35 dBA.

SSD Random Seeks Sound Pressure level is 19 dBA (fan off).

Integrated 3 Multi Array Microphone including world-facing 3 rd mic for noise suppression Audio Solution Codec Realtek ALC3292 + Discrete amp NXP9892

Camera

User facing FHD + IR camera – Front⁸ Integrated 8MP – Back

Webcam

IR Webcam LED Indicator

8. HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Elite x2 G4 Collaboration Keyboard

Pointing Device

Touchpad with multi-touch gesture enabled

Function Keys

Esc Key

F1 - Display Switching

F2 - Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Backlit Toggle

F10 - numlk

F11 - Wireless

F12 - Calendar

Share/Present

Call Answer

Call End

Delete

FN Key Lock

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

Fn+E - Insert

Fn+W - Pause



Technical Specifications

Clickpad Requirements:

Microsoft Precision Touchpad Default Gestures Support FW PTP with Filter Driver

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen5²³

HP Drive Lock & Automatic Drive Lock²⁴

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase²⁵

Absolute Persistence Module²⁶

Pre-boot Authentication

Software

HP Native Miracast Support²⁷

HP Connection Optimizer

HP Image Assistant

HP Hotkey Support

HP JumpStart

HP Support Assistant²⁸

HP Noise Cancellation Software

Buy Office (Sold separately)

Manageability Features

HP Driver Packs²⁹

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen3³⁰

HP Cloud Recovery³¹

Client Security Software

HP Client Security Suite Manager³²

HP Fingerprint Sensor (select models)33

HP Power On Authentication

Windows Defender³⁴

Security Management

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³⁵



Technical Specifications

SATA 0.1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Click³⁶

HP Sure Start Gen5³⁷

HP Sure Run Gen2³⁸

HP Sure Recover Gen2³⁹

HP Sure Sense⁴⁰

Security

TPM

Model: Infineon SLB9670

Version: 7.85

Revision: TPM 2.0

FIPS 140-2 Compliant: Yes

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

- 23. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
- 24. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives
- 25. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 26. Absolute agent is shipped turned off and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

- 27. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 28. HP Support Assistant requires Windows and Internet access.
- 29. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 30. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 31. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 32. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
- 33. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.
- 34. Windows Defender Opt in and internet connection required for updates.
- 35. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).re TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 36. HP Sure Click is available on select HP platforms and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office



Technical Specifications

or Adobe Acrobat are installed.

37. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.

38. HP Sure Run Gen2: See product specifications for availability.

39. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.

40. HP Sure Sense requires Windows 10. See product specifications for availability. On HP Elite x2 G4 units with WWAN shipping to China, HP Sure Sense is only available via Softpag download.

POWER

Power Supply

HP Smart 65 W USB Type-C[™] adapter⁴¹ HP Smart 65 W USB Type-C[™] slim adapter⁴¹

Primary Battery

HP Long Life 2-cell, 47 Wh Li-ion polymer⁴² Supports HP Fast Charging (Up to 50% in 30 mins)⁴³

Battery life

Up to 14 hours and 15 minutes⁴⁴

Power Cord

Duckhead

Duckhead Power Cord Length: AC = 1m

- 41. Availability may vary by country.
- 42. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 43. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

44. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight

Tablet (Imperial)

Tablet (Metric)

Starting at 1.83 lbs⁴⁵

Collaboration Travel Keyboard (Imperial)

Collaboration Travel Keyboard (Metric)

Tablet and Collaboration Travel Keyboard

Starting at 2.58 lb⁴⁵

Starting at 2.58 lb⁴⁵

(Imperial)

Tablet and Collaboration Travel Keyboard Starting at 1.17 kg⁴⁵

(Metric)

Product Dimensions (w x d x h)

Dimensions tablet (imperial) 11.39 x 8.51 x 0.35 in



Dimensions tablet (metric) 28.93 x 21.58 x 0.88 cm Dimensions tablet and Collaboration Travel 11.39 x 8.79 x 0.56 in

Keyboard(imperial)

Dimensions tablet and Collaboration Travel 28.93 x 22.32 x1.42 cm

Keyboard (metric)

45. Weight will vary by configuration.

PORTS/SLOTS

Ports

2 USB 3.1 Type-C[™] with Thunderbolt support 1 USB 3.1 Type-C[™] Gen 1 (Power delivery, DisplayPort[™] 1.2) 1 Headphone/Microphone Combo Nano Security Lock Slot (Lock sold separately)

Expansion Slots

1 Nano SIM

Sensors

Accelerometer
Magnetometer
Gyro
E-compass
ALS (ambient light sensor)
Hall Sensor

SERVICE AND SUPPORT

HP Services offers 1-year or 3 year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁴⁶

46. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19 V
	Average Operating Power	Win 10
	Integrated Graphics	6.78W
	Discrete Graphics	N/A
	Max Operating Power	UMA < 65W
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing optical)
	Non-operating	41° to 95° F (5° to 35° C) (writing optical)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	UL	Yes
Certifications	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR®	Yes ⁴⁷
	EPEAT® 2019	Yes, Gold in U.S. ⁴⁸
	ICES	Yes
	Australia / NZ A-Tick Compliance	Yes
	ccc	Yes
	Japan VCCI Compliance	Yes
	KC	Yes

(ICCP)

GOST

BSMI

CIT

SABS Yes UKRSERTCOMPUTER Yes

Saudi Arabian Compliance Yes

CE Marking Compliance

BNCI or BELUS

47. Configurations of the HP Elite x2 G4 that are ENERGY STAR® certified are identified as HP Elite x2 G4 ENERGY STAR® on HP websites and on http://www.energystar.gov.

48. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

Yes

Yes

Yes

Yes

Yes



DISPLAYS

Panel LCD 12.3 inch diagonal WUXGA+ (1920 x 1280) BrightView WLED UWVA 72% NTSC 400 nits eDP 1.4+PSR Ultraslim Outline Dimensions (W x H x D)265.56 x 185.06 mm (max)Active Area259.2 x 172.8 mm (typ.)

Weight 161 g (max)
Diagonal Size 12.3 inch

Thickness 1.96 mm (panel side) / 4.59 mm (max)

InterfaceeDP 1.4a + PSR (2 lane)Surface TreatmentBright-View (BV)

Touch Enabled Yes

Contrast Ratio 1200:1 (typ.)

Refresh Rate 60Hz Brightness 400 nits

Pixel Resolution 1920 x 1280 (WUXGA+)

Format RGB Backlight LED

Color Gamut Coverage 72% of NTSC

Color Depth 6bits

Viewing Angle UWVA 85/85/85

13" diagonal 3kx2k IPS LED-backlit touch screen with Corning® Gorilla® Glass 4 Low Power Ultra Slim bent 450 nits 72% NTSC (3000 x 2000) Outline Dimensions (W x H x D) 279.3 x 193.0 mm (max)
Active Area 274.5 x 183 mm (max)

Weight 160 g (max)
Diagonal Size 13.0"

Thickness 1.8 (panel side)/3.9 (PCBA side) mm(max)

InterfaceeDPSurface TreatmentGlareTouch EnabledYes

Contrast Ratio 1800 (typ.)
Refresh Rate 60Hz

Brightness 450 nits typical (Panel Only)

Pixel Resolution 3000 x 2000
Format RGB stripe

Backlight LED

Color Gamut Coverage 72% of NTSC **Color Depth** 6 bits

Viewing Angle 85/85/85



13" diagonal WUXGA+ (1920 x 1280) BrightView **WLED UWVA**

72% NTSC 1000 nits eDP 1.4+PSR2 bent Privacy

Gen3

Outline Dimensions (W x H x D) 277.748 x 193.2 mm (max) **Active Area** 272.448 x 191.632 mm (tvp.)

Weight 190 q (max) **Diagonal Size** 13.0 inch **Thickness** 3.9 mm (max)

Interface eDP 1.4 + PSR2 (4 lane)

Surface Treatment BrightView (BV)

Touch Enabled Yes

Contrast Ratio 2000:1 (tvp.) **Refresh Rate** 60 Hz

Brightness 1000 nits

Pixel Resolution 1920 x 1280 (WUXGA+)

Format RGB Backlight LED **Color Gamut Coverage 72% NTSC Color Depth** 8 bits

Viewing Angle UWVA 85/85/85/85

13" diagonal WUXGA+ (1920 x 1280) BrightView

WLED UWVA

72% NSTC 650 nits eDP 1.4a ultraslim Privacy Gen2

Outline Dimensions (W x H x D) 279.3 x 193.2 mm (max.)

Active Area 272.449 x 181.632 mm (max.)

Weight 220g (max.) **Diagonal Size** 13.0"

Thickness 3.9 mm(max.) Interface eDP 1.4a **Surface Treatment** BrightView (BV)

Touch Enabled

Contrast Ratio Sharing mode, 600:1 (typ.)

Privacy mode, 150:1 (typ.)

Refresh Rate 120 Hz

Brightness Sharing mode, 650 nits (typ.)

Privacy mode, 320 nits (typ.)

Pixel Resolution 1920 x 1280 (WUXGA+)

Format RGB Backlight LED

Color Gamut Coverage Sharing mode, 72% NTSC

Privacy mode, 60% NTSC

Color Depth 6 bits + Hi FRC

Viewing Angle Sharing mode, CR > 10, L/R/U/D, 85/85/85/85 (tvp.)

Privacy mode CR>2, L/R/U/D, 50/50/85/85 (typ.)



STORAGE AND DRIVES

SSD 128 GB 2280 M2 SATA- Form Factor 3 TLC

Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

 $\begin{array}{lll} \mbox{Height} & 0.09 \mbox{ in (2.3 mm)} \\ \mbox{Width} & 0.87 \mbox{ in (22 mm)} \\ \mbox{Weight} & 0.02 \mbox{ lb (10 g)} \\ \mbox{Interface} & \mbox{ATA-8, SATA 3.0} \\ \mbox{Maximum Sequential Read} & 540 \mbox{ MB/s} {\sim} 560 \mbox{ MB/s} \\ \mbox{Maximum Sequential Write} & 500 \mbox{ MB/s} {\sim} 530 \mbox{ MB/s} \\ \end{array}$

Logical Blocks 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

SSD 1 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up To 2800 MB/s

 Maximum Sequential Write
 Up To 1600 MB/s

 Logical Blocks
 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TRIM; L1.2

SSD 256 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 2580 MB/s ~ 2600 MB/s

 Maximum Sequential Write
 900 MB/s ~ 1000 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TRIM; L1.2



SSD 256 GB 2280 M2 SATA- Form Factor
3 Self Encrypted OPAL2 Capacity
Three Layer Cell

Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

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Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP

SSD 2 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided Form Factor M.2 2280
Capacity 2 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCle NVMe Gen3X4

 Maximum Sequential Read
 Up To 3000 MB/s

 Maximum Sequential Write
 Up To 2100 MB/s

 Logical Blocks
 3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP

SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 2800 MB/s ~ 2900 MB/s

 Maximum Sequential Write
 1000 MB/s ~ 1800 MB/s

Logical Blocks 1,000,215,215

Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security (Option); TRIM; L1.2



SSD 512 GB 2280 PCIe-3x4 Form Factor NVMe Self Encrypted OPAL2 Capacity Three Layer Cell

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read2800 MB/s \sim 2900 MB/sMaximum Sequential Write1000 MB/s \sim 1800 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

SSD 512 GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp To 1500 MB/sLogical Blocks1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 256 GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 1700 MB/s
Maximum Sequential Write Up to 1300 MB/s
Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



512 GB 2280 PCIe-3x2x2 Form Fac NVMe+SSD 32 GB 3D Xpoint Capacity

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up To 2400 MB/s

 Maximum Sequential Write
 Up To 1300 MB/s

 Logical Blocks
 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



NETWORKING/COMMUNICATIONS

intel° 22260
802.11a/b/g/n/ac/ax
(2x2) Wi-Fi 6* and
Bluetooth® 5.1 Combo
vPro

1-4-10 22260

Wireless LAN Standards IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11d IEEE 802.11e

IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11r

Interoperability Wi-Fi® certified
Frequency Band •802.11b/g/n/ax

2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security²
•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

•Cisco Certified Extensions, all versions through CCX4 and CCX Lite

•WAPI

Network Architecture

Models Roaming

Output Power¹

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

802.11b: +18.5dBm minimum802.11g: +17.5dBm minimum

• 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum



802.11ac VHT160(5GHz): +11.5dBm minimum
 802.11ax HT40(2.4GHz): +10dBm minimum
 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption •Transmit mode 2.0 W

•Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode 50 mW (WLAN unassociated)

•Connected Standby 10mW
•Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum
• 802.11a/g, 6Mbps: -86dBm maximum
• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
• 802.11ac, MCS0: -84dBm maximum
• 802.11ac. MCS9: -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8 g

2. Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Amber – Radio OFF; LED White – Radio ON

- 1. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 2. Check latest software/driver release for updates on supported security features.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

*Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.



HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH) Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps

BLE: 1 Mbps signaling data rate¹ 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C. Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

For full Intel® vPro™ functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See http://Intel.com/vpro.



Intel® 22260 802.11a/b/g/n/ac/ax (2 x 2) Wi-Fi 6* and Bluetooth® 5.1 Combo Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11d
IEEE 802.11h
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k

IEEE 802.11r IEEE 802.11v Wi-Fi® certified

Interoperability Frequency Band

•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz

Data Rates

•802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security² •IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode

only

AES-CCMP: 128 bit in hardware

802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

IEEE 802.11 compliant roaming between access points

•WPA2 certification •IEEE 802.11i

•Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

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Infrastructure (Access Point Required)

Output Power¹ • 802.11b: +18.5dBm minimum

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum

• 802.11ac VHT80(5GHz): +11.5dBm minimum



802.11ac VHT160(5GHz): +11.5dBm minimum
 802.11ax HT40(2.4GHz): +10dBm minimum
 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption •Transmit mode 2.0 W

•Receive mode 1.6 W

Idle mode (PSP)180 mW (WLAN Associated)Idle mode 50 mW (WLAN unassociated)

•Connected Standby 10mW
•Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

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•802.11b, 11Mbps: -84dBm maximum
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• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
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• 802.11ac, MCS9: -59dBm maximum

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Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

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Altitude Operating 0 to 10,000 ft (3,048 m)

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LED Activity LED Amber – Radio OFF; LED White – Radio ON

- 1. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
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1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

Microsoft Windows ACPI, and USB Bus Support

a maximum transmit power of + 9.5 dBm for BR and EDR.

Peak (Tx) 330 mW **Power Consumption**

> Peak (Rx) 230 mW Selective Suspend 17 mW

Bluetooth Software Supported

Microsoft Windows Bluetooth Software

Power Management

Certifications FCC (47 CFR) Part 15C. Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

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LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Intel® XMM™ 7360 LTE-Advanced CAT91

Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300

(Band 30), 1700/2100 (Band 66).



TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up

to 450Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum powerLTE: 1,200 mA (peak); 900 mA (average)consumptionHSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 g

Dimensions

(Length x Width x

42 x 30 x 2.3 mm

Thickness)

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel® XMM™ 7560 LTE-Advanced Pro DL CAT16¹ Technology/Operating

bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only),

2300 (Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41), 3500 (Band 42), 5200 (Band 46 RX only)

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW

throughput up to 978Mbps; UL-CAT.7 20MHz throughput up to 75Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

MHz

Maximum data rates LTE: 978 Mbps (Download), 75 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm



Technical Specifications

Maximum power LTE: 1.200 mA (peak): 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) consumption

Form Factor M.2, 3042-S3 Key B

Weight 6 q

Dimensions

(Length x Width x 42 x 30 x 2.3 mm

Thickness)

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP Graff GNSS Module Technology Standalone GPS, GLONASS

> Dimensions (L x W x H) 42 x 30 x 2.3 mm

System interface **USB 2.0**

GPS bands GPS L1 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz Power Consumption Active mode (continuous): 67 mA (peak): 26 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 4.3 q

POWER

AC Adapter 65 Watt nPFC Dimensions (H x W x D) Slim USB type C Straight 1.8m

88.0 x 53.5 x 21.0 mm

Weight Input

Output

220 q +/- 10 q 100 to 240 VAC

Input Efficiency

Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5V: 81.5% 9V: 86.7% 12V: 88.0% 15V: 89.0% 20V: 89.0%

Input frequency range 48 ~ 63 Hz

Input AC current Max. 1.7 A at 90 VAC

Output power 5V/15W

9V/27W 12V/60W 15V/65W 20V/65W

DC output 5V / 9V / 12V / 15V / 20V Hold-up time 5 ms at 115 Vac input

Output current limit <8.0A

Connector **USB Type-C**



Environmental Design Operating 8 4 1 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

CE Mark - full compliance with LVD and EMC directives **EMI and Safety** Certifications

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

> FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200.000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions (H x W x D) USB type C Straight 1.8 m C6NS (Hades+)

Weight Input

74 x 74 x 28.5 mm

245 q +/- 10 q 100 to 240 VAC

Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

> 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

1.7 A at 90 VAC and maximum load Input AC current

Output power 65W

DC output 5V/9V/10V/12V/15V/20V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector Non-Standard C6

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B.

FCC Class B. CISPR22 Class B. CCC. NOM-1 NYCE.

MTBF - over 100,000 hours at 25°C ambient condition.



Technical Specifications

Battery MR 2 Cell WHr 47 Dimensions $(H \times W \times L)$

Long Life -PL Fast

Charge

imensions (H x W x L) 5.11 x 84.00 x 238.14 mm

Weight 0.190 kg

Cells/Type 4cell Lithium-Ion Polymer cell / 4473A9

Energy Voltage 7.7 V

No

Amp-hour capacity 6.15 Ah

Watt-hour capacity 47 Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 122° F (-10° to 60° C)

Fuel Gauge LED NA

Warranty 3-year

Optional Travel Battery

Available



Country of Origin

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Docking	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock w/Combo Cable G2	3TR87AA
	HP Thunderbolt Dock w/Audio Module	3YE87AA
	HP Audio Module	3AQ21AA
	HP Thunderbolt Dock 120W Cable	3XB94AA
	HP Thunderbolt Dock Combo Cable	3XB96AA
	HP Thunderbolt Dock	1DT93AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock Non Flash	3DV65AA
	HP USB-C Mini Dock	1PM64AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Conferencing Keyboard	K8P74AA
	HP Elite x2 G4 Collaboration Keyboard	7CS01AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Slim Bluetooth Mouse	F3J92AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Elite Presenter Mouse	2CE30AA
	HP Rechargeable Active Pen G3	6SG43AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB 3.0 PN	N2Z63AA
	HP USB-C to HDMI	1WC36AA
	HP USB-C to DP	N9K78AA
	HP USB-C to VGA	N9K76AA
	HP RJ45 Adapter PN	V7W66AA
Power	HP 65W USB-C Power Adapter	1HE08AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP USB-C Notebook Power Bank	2NA10AA



Options and Accessories (sold separately and availability may vary by country)

Security	HP Nano Keyed Cable Lock HP Nano Dual-Head Keyed Cable Lock	1AJ39AA 1AJ41AA
UCC	HP UC Speaker Phone	4VW02AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA

HP UC Wireless Mono Headset W3K08AA
HP UC Wireless Duo Headset W3K09AA



Change Log

Date of change:	Version History:		Description of change:
August 1, 2019	From V1 to V2	Updated	Sure Sense disclaimer
August 7, 2019	From V2 to V3	Updated	Displays section
September 9, 2019	From V3 to V4	Added	Intel® Optane™ and disclaimer for 1000 nit Sure View panel
October 4, 2019	From V4 to V5	Updated	Ports, Battery and Weight Sections
November 6, 2019	From V5 to V6	Updated	Keyboard
November 13, 2019	From V6 to V7	Updated	Security Section
January 6, 2020	From V7 to V8	Updated	Collaboration Keyboard weight
February 21, 2020	From V8 to V9	Added	Two panels in display section
February 27, 2020	From V9 t oV10	Updated	Copyright and footnote for fingerprint sensor
March 4, 2020	From V10 to V11	Removed	Power Bank, Accessories Section
October 19, 2020	From V11 to V12	Updated	Display section
December 14, 2020	From V12 to V13	Updated	MIL Updated

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